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(71) Applicant: **CABOT MICROELECTRONICS CORPORATION** [US/US]; Legal Department, 870 North Commons Drive, Aurora, IL 60504 (US).

(72) Inventor: **PRASAD, Abaneshwar**; c/o Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, IL 60504 (US).

(74) Agents: **WESEMAN, Steven** et al.; Associate General Counsel, Intellectual Property, Cabot Microelectronics Corporation, 870 North Commons Drive, Aurora, IL 60504 (US).

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(54) Title: LOW SURFACE ENERGY CMP PAD

(57) Abstract: The invention provides a polishing pad substrate comprising a copolymer, wherein the copolymer has at least one hydrophilic repeat unit and at least one hydrophobic repeat unit. The invention also provides a polishing pad substrate comprising a polymer, wherein the polymer is a modified polymer having at least one hydrophilic unit and at least one hydrophobic unit attached to the polymer chain. The invention further provides a method of polishing a workpiece comprising (i) providing a workpiece to be polished, (ii) contacting the workpiece with a chemical-mechanical polishing system comprising the polishing pad substrate of the invention, and (iii) abrading at least a portion of the surface of the workpiece with the polishing system to polish the workpiece.

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